



30V N-CHANNEL ENHANCEMENT MODE MOSFET

Product Summary

BVDSS	Rds(on) Max	I _D Max T _A = +25°C
30V	5.5mΩ @ V _{GS} = 10V	15A
30 V	7.5mΩ @ V _{GS} = 4.5V	13A

Features and Benefits

- Low On-Resistance
- Low Input Capacitance
- Fast Switching Speed
- 100% Unclamped Inductive Switching (UIS) Test in Production Ensures More Reliable and Robust End Application
- Totally Lead-Free & Fully RoHS Compliant (Notes 1 & 2)
- Halogen and Antimony Free. "Green" Device (Note 3)
- For automotive applications requiring specific change control (i.e. parts qualified to AEC-Q100/101/104/200, PPAP capable, and manufactured in IATF 16949 certified facilities), please contact us or your local Diodes representative. https://www.diodes.com/quality/product-definitions/

Description and Applications

This MOSFET is designed to minimize the on-state resistance (R_{DS(ON)}) yet maintain superior switching performance, making it ideal for high-efficiency power-management applications.

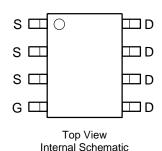
- Motor controls
- Backlighting
- Power-management functions
- DC-DC converters

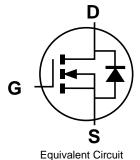
Mechanical Data

- Package: SO-8
- Package Material: Molded Plastic, "Green" Molding Compound.
 UL Flammability Classification Rating 94V-0
- Moisture Sensitivity: Level 3 per J-STD-020
- Terminal Connections Indicator: See Diagram Below
- Terminals: Finish—Matte Tin Annealed over Copper Leadframe.
 Solderable per MIL-STD-202, Method 208 63
- Weight: 0.074 grams (Approximate)









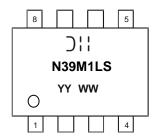
Ordering Information (Note 4)

Part Number	Packing			
Part Number	Package	Qty.	Carrier	
DMN39M1LSS-13	SO-8	2,500	Tape & Reel	

Notes: 1. No purposely added lead. Fully EU Directive 2002/95/EC (RoHS), 2011/65/EU (RoHS 2) & 2015/863/EU (RoHS 3) compliant.

- 2. See https://www.diodes.com/quality/lead-free/ for more information about Diodes Incorporated's definitions of Halogen- and Antimony-free, "Green" and Lead-free.
- 3. Halogen- and Antimony-free "Green" products are defined as those which contain <900ppm bromine, <900ppm chlorine (<1500ppm total Br + Cl) and <1000ppm antimony compounds.
- 4. For packaging details, go to our website at https://www.diodes.com/design/support/packaging/diodes-packaging/.

Marking Information



);; = Manufacturer's Marking
N39M1LS = Product Type Marking Code
YYWW = Date Code Marking
YY or YY = Year (ex: 23 = 2023)
WW = Week (01 to 53)



Maximum Ratings (@T_A = +25°C, unless otherwise specified.)

Characteristic			Symbol	Value	Unit
Drain-Source Voltage			VDSS	30	V
Gate-Source Voltage	Vgss	±20	V		
Continuous Drain Current (Note 5) Vgs = 10V	lo	15 12	А		
Pulsed Drain Current (10µs Pulse, Duty Cycle = 1%)	I _{DM}	128	Α		
Maximum Continuous Body Diode Forward Current (Is	2.2	Α		
Avalanche Current (Note 6) L = 0.1mH			las	38	Α
Avalanche Energy (Note 6) L = 0.1mH			Eas	72	mJ

Thermal Characteristics (@TA = +25°C, unless otherwise specified.)

Characteristic			Symbol	Value	Unit
Total Power Dissipation (Note 7)	Steady State	T _A = +25°C	PD	1.4	W
Thermal Resistance, Junction to Ambient (Note 7)	Steady State	Reja	84	°C/W	
Total Power Dissipation (Note 5) Steady State		$T_A = +25$ °C	PD	1.9	W
Thermal Resistance, Junction to Ambient (Note 5) Steady Sta			$R_{\theta JA}$	62	°C/W
Thermal Resistance, Junction to Case (Note 5)			Rejc	7.5	C/VV
Operating and Storage Temperature Range			TJ, TSTG	-55 to +150	°C

Electrical Characteristics (@T_A = +25°C, unless otherwise specified.)

Characteristic	Symbol	Min	Тур	Max	Unit	Test Condition	
OFF CHARACTERISTICS (Note 8)							
Drain-Source Breakdown Voltage	BVDSS	30		_	V	$V_{GS} = 0V, I_{D} = 250\mu A$	
Zero Gate Voltage Drain Current	IDSS	_	_	1	μΑ	V _{DS} = 30V, V _{GS} = 0V	
Gate-Source Leakage	Igss	_	_	±100	nA	$V_{GS} = \pm 20V$, $V_{DS} = 0V$	
ON CHARACTERISTICS (Note 8)							
Gate Threshold Voltage	Vgs(TH)	1	1.4	2.5	V	V _{DS} = V _{GS} , I _D = 250µA	
Static Drain-Source On-Resistance	D	_	3.8	5.5	mΩ	V _G S = 10V, I _D = 15A	
Static Drain-Source On-Resistance	RDS(ON)	_	5.0	7.5	mt7	V _{GS} = 4.5V, I _D = 15A	
Diode Forward Voltage	V _{SD}	_	0.7	1.2	V	V _{GS} = 0V, I _S = 1A	
DYNAMIC CHARACTERISTICS (Note 9)							
Input Capacitance	Ciss	_	2311	_	pF		
Output Capacitance	Coss	_	304	_	pF	V _{DS} = 15V, V _{GS} = 0V f = 1.0MHz	
Reverse Transfer Capacitance	Crss	_	242	_	pF	1 = 1.0WI IZ	
Gate Resistance	Rg	_	2.4	_	Ω	$V_{DS} = 0V, V_{GS} = 0V, f = 1.0MHz$	
Total Gate Charge (VGS = 4.5V)	Qg	_	21	_	nC		
Total Gate Charge (V _{GS} = 10V)	Qg	_	42	_	nC	\/ 45\/ I- 45\	
Gate-Source Charge	Qgs	_	7	_	nC	V _{DS} = 15V, I _D = 15A	
Gate-Drain Charge	Qgd	_	7	_	nC	1	
Turn-On Delay Time	t _{D(ON)}	_	5.7	_	ns		
Turn-On Rise Time	t _R	_	16.3	_	ns	V _{DD} = 15V, V _{GS} = 10V	
Turn-Off Delay Time	tD(OFF)	_	45.4	_	ns	$R_g = 3.3\Omega, I_D = 15A$	
Turn-Off Fall Time	tF	_	20.9	_	ns	1	
Reverse Recovery Time	t _{RR}	_	20.5	_	ns	- 450 dl/dk 4000/	
Reverse Recovery Charge	Q _{RR}	_	9.0		nC	I _F = 15A, dI/dt = 100A/μs	

Notes:

- Device mounted on FR-4 substrate PCB, 2oz copper, with 1inch square copper plate.
 I_{AS} and E_{AS} ratings are based on low frequency and duty cycles to keep T_J = +25°C.
 Device mounted on FR-4 substrate PCB, 2oz copper, with minimum recommended pad layout.
 Short duration pulse test used to minimize self-heating effect.
- 9. Guaranteed by design. Not subject to product testing.



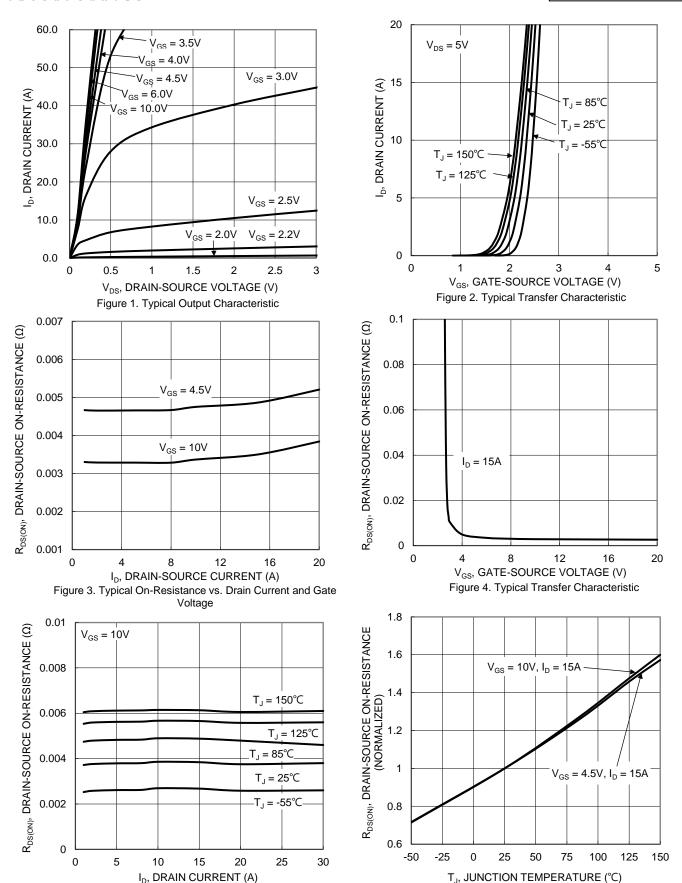


Figure 5. Typical On-Resistance vs. Drain Current and Junction Temperature

Figure 6. On-Resistance Variation with Junction Temperature



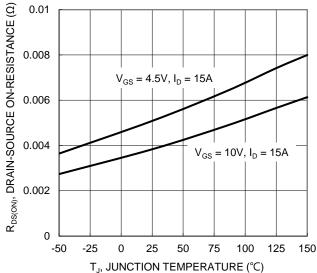
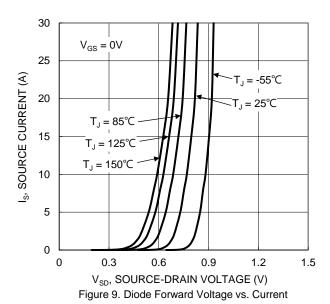
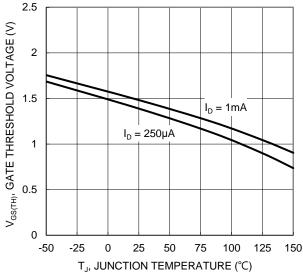


Figure 7. On-Resistance Variation with Junction Temperature



10 8 6 $V_{GS}(V)$ 4 $V_{DS} = 15V, I_{D} = 15A$ 2 0 5 0 10 15 20 25 30 35 40 45 Q_g (nC) Figure 11. Gate Charge



 $T_{\rm J},$ JUNCTION TEMPERATURE (°C) Figure 8. Gate Threshold Variation vs. Junction Temperature

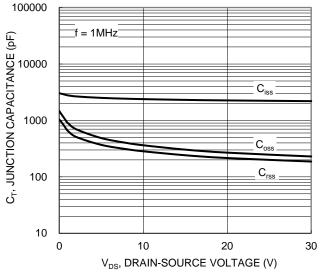
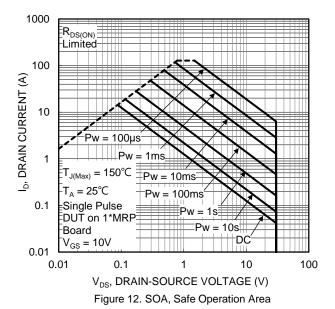


Figure 10. Typical Junction Capacitance





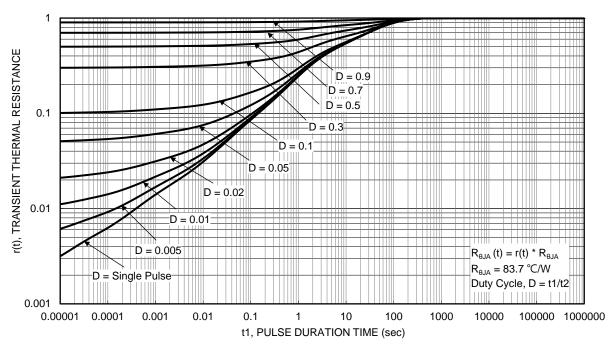


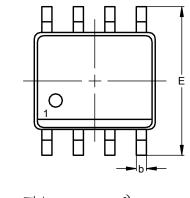
Figure 13. Transient Thermal Resistance

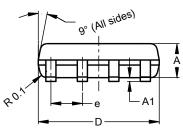


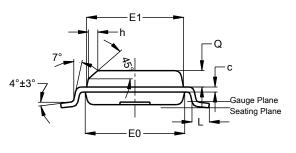
Package Outline Dimensions

Please see http://www.diodes.com/package-outlines.html for the latest version.

SO-8





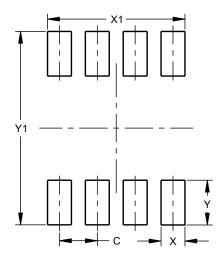


SO-8						
Dim	Min	Max	Тур			
Α	1.40	1.50	1.45			
A 1	0.10	0.20	0.15			
b	0.30	0.50	0.40			
С	0.15	0.25	0.20			
D	4.85	4.95	4.90			
Е	5.90	6.10	6.00			
E1	3.80	3.90	3.85			
E0	3.85	3.95	3.90			
е		1	1.27			
h			0.35			
L	0.62	0.82	0.72			
Ø	0.60	0.70	0.65			
All Dimensions in mm						

Suggested Pad Layout

Please see http://www.diodes.com/package-outlines.html for the latest version.

SO-8



Dimensions	Value (in mm)		
С	1.27		
Х	0.802		
X1	4.612		
Y	1.505		
V1	6.50		



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